

HSU277

Silicon Epitaxial Planar for UHF/VHF tuner Band Switch

REJ03G0111-0800Z
(Previous: ADE-208-018G)
Rev.8.00
Oct.08.2003

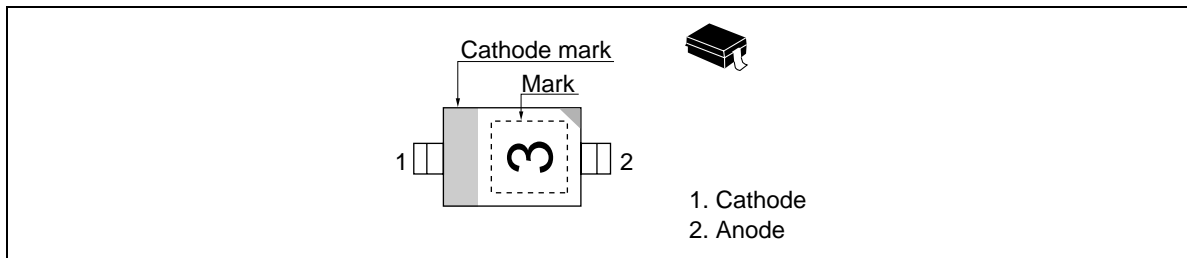
Features

- Low forward resistance. ($r_f = 0.7 \Omega$ max)
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSU277	3	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

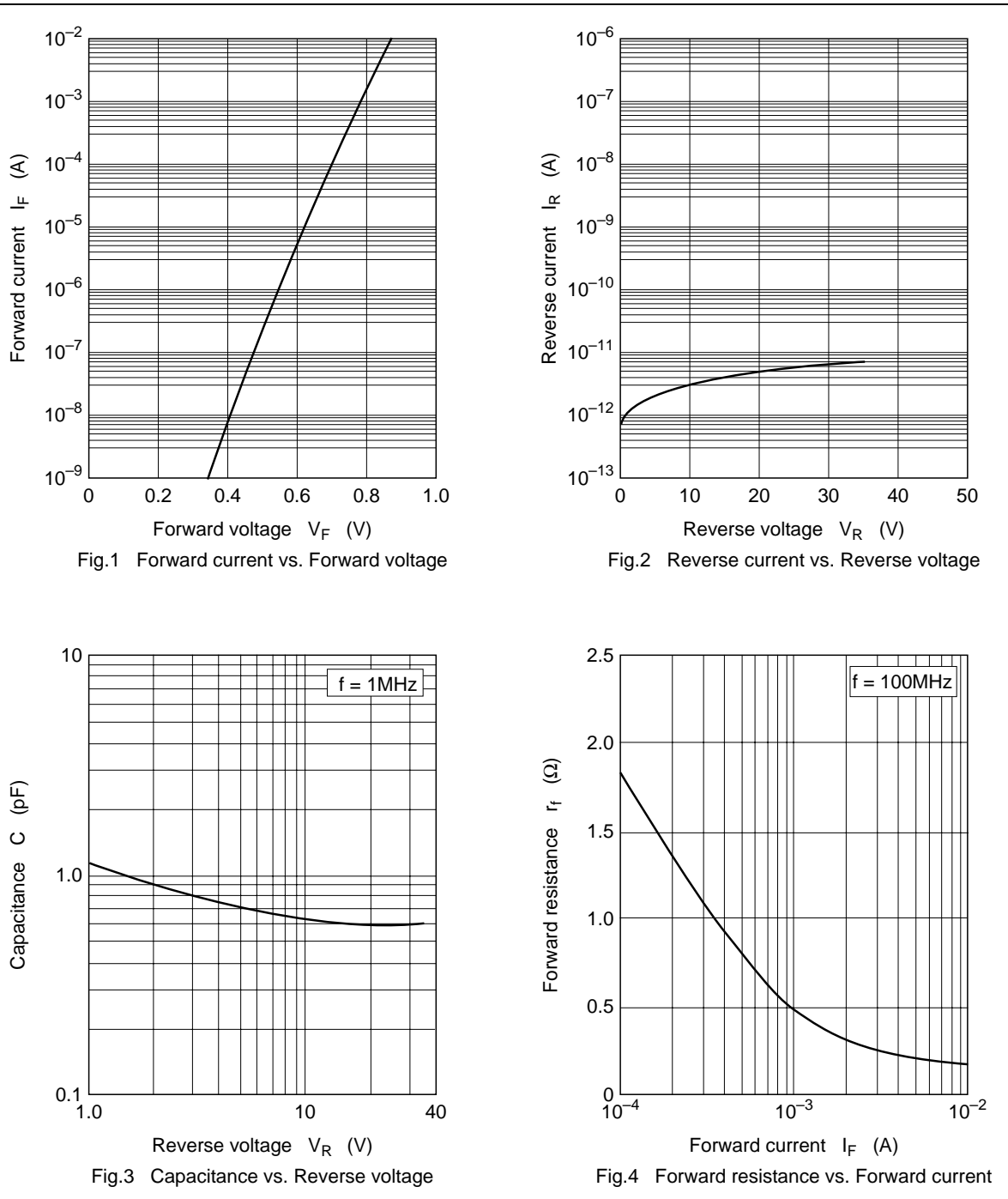
Item	Symbol	Value	Unit
Reverse voltage	V _R	35	V
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-45 to +125	°C
Operation temperature	Topr	-20 to +60	°C

Electrical Characteristics

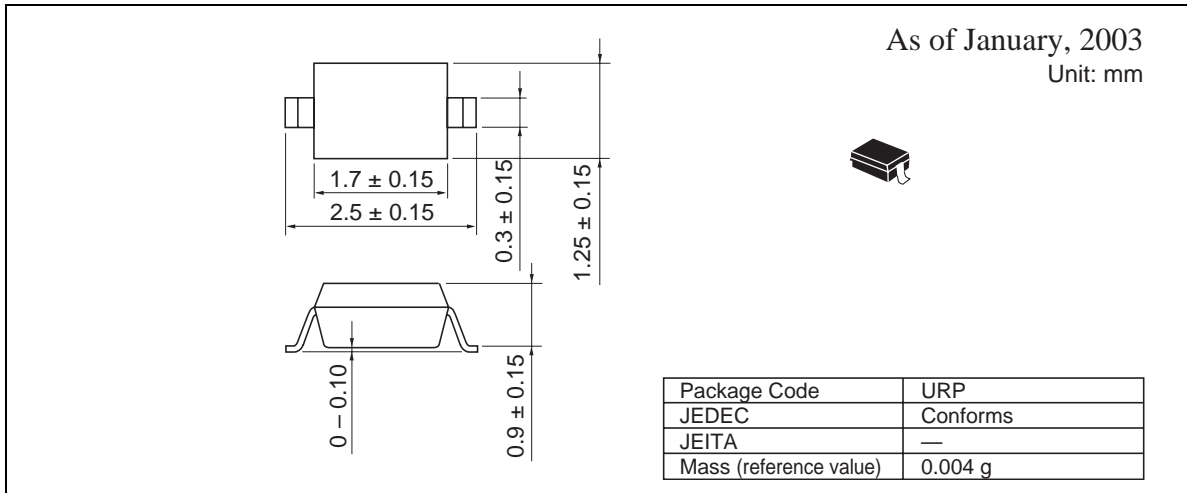
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V _R	35	—	—	V	I _R = 10 μA
Forward voltage	V _F	—	—	1.0	V	I _F = 10 mA
Reverse current	I _R	—	—	50	nA	V _R = 25 V
Capacitance	C	—	—	1.2	pF	V _R = 6 V, f = 1 MHz
Forward resistance	r _f	—	—	0.7	Ω	I _F = 2 mA, f = 100 MHz

Main Characteristic



Package Dimensions



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